

ABSTRACT

In a slurry for cutting a silicon ingot according to the present invention, a content of a basic material is at least 3.5% by mass with respect to the total mass of a liquid component of a slurry, organic amine is contained in a mass ratio of 0.5 to 5.0 with respect to water in a liquid component of the slurry, and pH of the slurry is 12 or more. Furthermore, according to a method of cutting a silicon ingot according to the present invention, the above-mentioned slurry for cutting a silicon ingot is used at 65°C to 95°C. Consequently, the cutting resistance during cutting processing of a silicon ingot is reduced, and a wafer of high quality can be obtained efficiently.